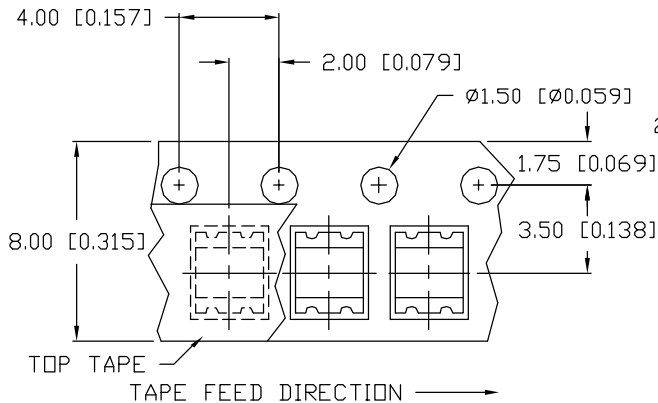
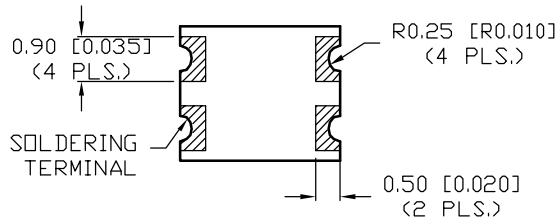
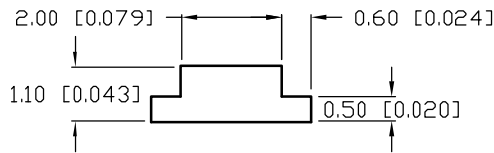
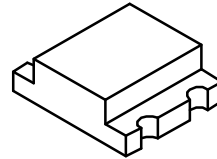
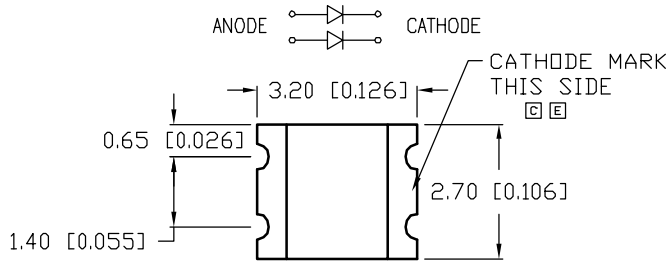


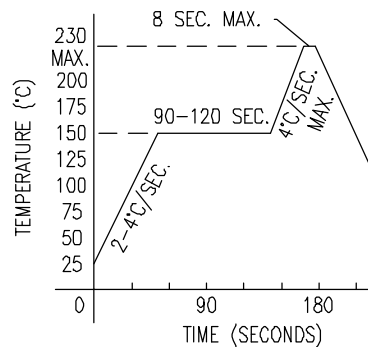
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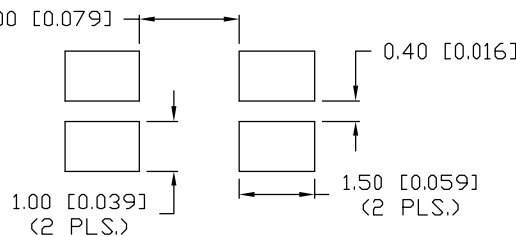
REV.  
F



REFLOW PROFILE



RECOMMENDED SOLDER PAD LAYOUT



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	$V_f$	
REVERSE VOLTAGE	4.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		15		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		160		$2x \theta_{\text{max}}$	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$  PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	80	mW
DERATE FROM $25^\circ\text{C}$	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING TEMP.	-25 TO +85	$^\circ\text{C}$
STORAGE TEMP.	-30 TO +85	$^\circ\text{C}$

\*  $t < 10\mu\text{s}$

NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION MAX.= +0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. F PART NUMBER SML-LX1210SR SRC-TR

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2.7mm x 3.2mm P.C.B. SURFACE MOUNT LED,  
DUAL 660nm SUPER RED CHIPS, WATER CLEAR LENS,  
TAPE AND REEL, 2,000 PIECES PER REEL.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT CHECKED BY: APPROVED BY: DATE: 4.21.95  
PAGE: 1 OF 1  
SCALE: N/A